

**I claim**

1. A heat dissipation module for a CPU, suitable for installation above the CPU and base socket, comprising:

a heat dissipation device, having a plurality of heat dissipation fins,

5 flowing paths being formed between the fins;

a fan fixing frame, fixed above the heat dissipation device, the fan fixing frame having a top plate, two side plates, a plurality of the elastic pressing components and at least one positioning elastic strip, the two side plates extending from opposite sides of the top plate, the two side plates extending to  
10 form a pulling portion and a plurality of clipping portions, the elastic pressing components being installed on the top plate, the positioning elastic strip being installed on the top plate, and the positioning elastic trip forming at least two pushing portions to touch an outer surface of the two side plates; and

a fan fixed on the top plate of the fan fixing frame;

15 wherein the fan fixing frame is installed above the base socket by using the clipping portions to connect with related clipping arms on the two sides of the base socket, the elastic pressing components having the elastic force to press the heat dissipation device onto the heat exhausting surface of the CPU.

2. The heat dissipation module for a CPU as claimed in claim 1, wherein  
20 the heat dissipation device has a through hole with a shape feature of penetrating the heat dissipation device from top to bottom, the flowing paths having connection paths through the bottom, top and outer side of the heat dissipation device, a side wall of the through hole having an air-flowing guiding surface at a top area and a plurality of air guiding holes at a bottom

area, the air guiding holes connecting with the flowing paths.

3. The heat dissipation module for a CPU as claimed in claim 2, wherein a heat transferring plate is installed in a bottom position to face the through hole of the heat dissipation device and contact the heat exhausting surface of the  
5 CPU.

4. The heat dissipation module for a CPU as claimed in claim 1, wherein the fan fixing frame has a opening hole and four connection holes, and the fan faces the opening hole and uses four screws to penetrate four corners of the fan fixing frame by screw connection at related connection holes.

10 5. The heat dissipation module for a CPU as claimed in claim 1, wherein the pulling portion of the fan fixing frame is formed by outer extension of the two side plates, the pulling portion having a free and upper end, the clipping portion being formed by downward extension of the two side plates.

6. The heat dissipation module for a CPU as claimed in claim 1, wherein  
15 the elastic pressing component comprises a connection part and a spring, the connection part having a hook portion on an upper side and a pressing portion on a lower side, the spring surrounding the connection part, the hook portion being inserted into a related piercing hole on the top plate of the fan fixing frame, and the spring being located between the top plate and the pressing  
20 portion.